



# MTD ETL sensor test setup at USTC

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# Outline

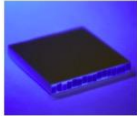
1. Introduction of the MTD ETL Project
2. Post process for wafers
3. ETL LGAD QA&QC plan
4. Test environment in USTC
5. Preliminary test results
6. Summary

# Introduction of the MTD Project

The CMS is going to introduce a new timing detector to measure timing of minimum ionizing particles (MIP) during the High Luminosity LHC (HL-LHC) era. The MIP Timing Detector (MTD) will reduce the effects of up to 200 pileup per bunch crossing, and thus, will provide better reconstruction of particles, and new capabilities for searches for the long-lived particles.

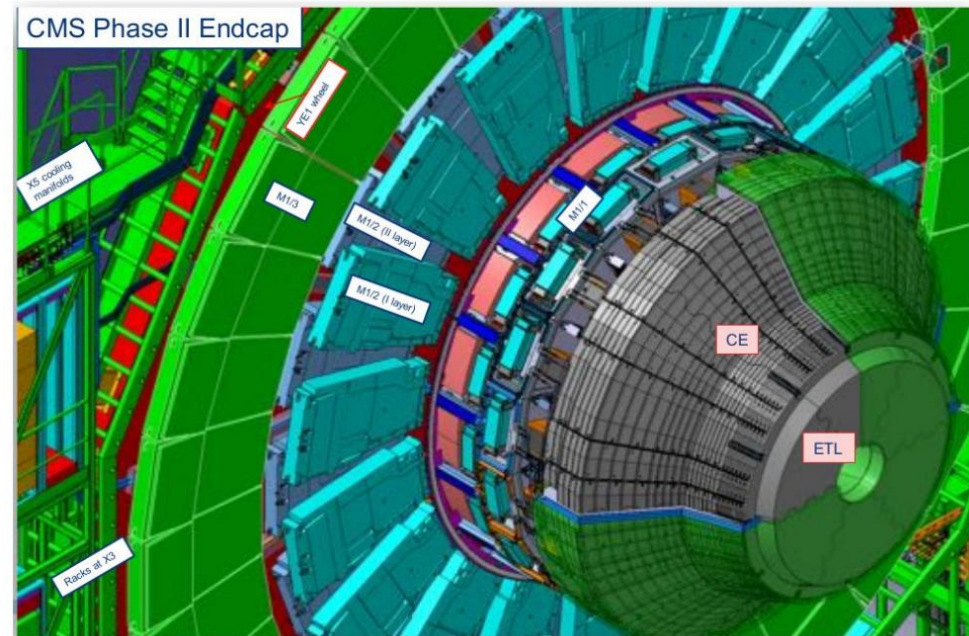
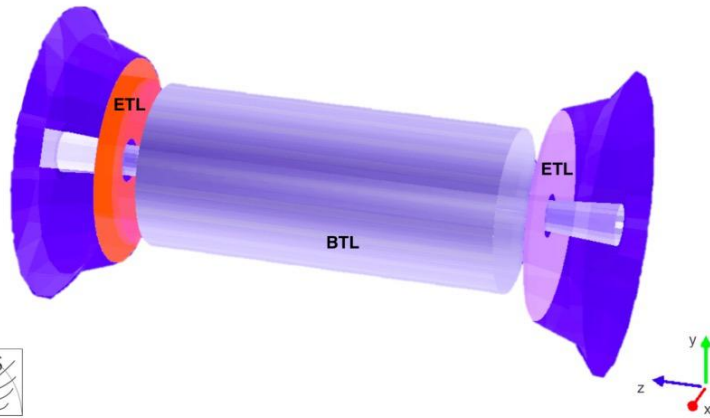
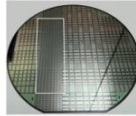
## BTL: LYSO bars + SiPM readout:

- TK / ECAL interface:  $|n| < 1.45$
- Inner radius: 1148 mm (40 mm thick)
- Length:  $\pm 2.6$  m along z
- Surface  $\sim 38$  m<sup>2</sup>; 332k channels
- Fluence at 4 ab<sup>-1</sup>:  $2 \times 10^{14}$  n<sub>eq</sub>/cm<sup>2</sup>



## ETL: Si with internal gain (LGAD):

- On the CE nose:  $1.6 < |n| < 3.0$
- Radius:  $315 < R < 1200$  mm
- Position in z:  $\pm 3.0$  m (45 mm thick)
- Surface  $\sim 14$  m<sup>2</sup>;  $\sim 8.5$ M channels
- Fluence at 4 ab<sup>-1</sup>: up to  $2 \times 10^{15}$  n<sub>eq</sub>/cm<sup>2</sup>



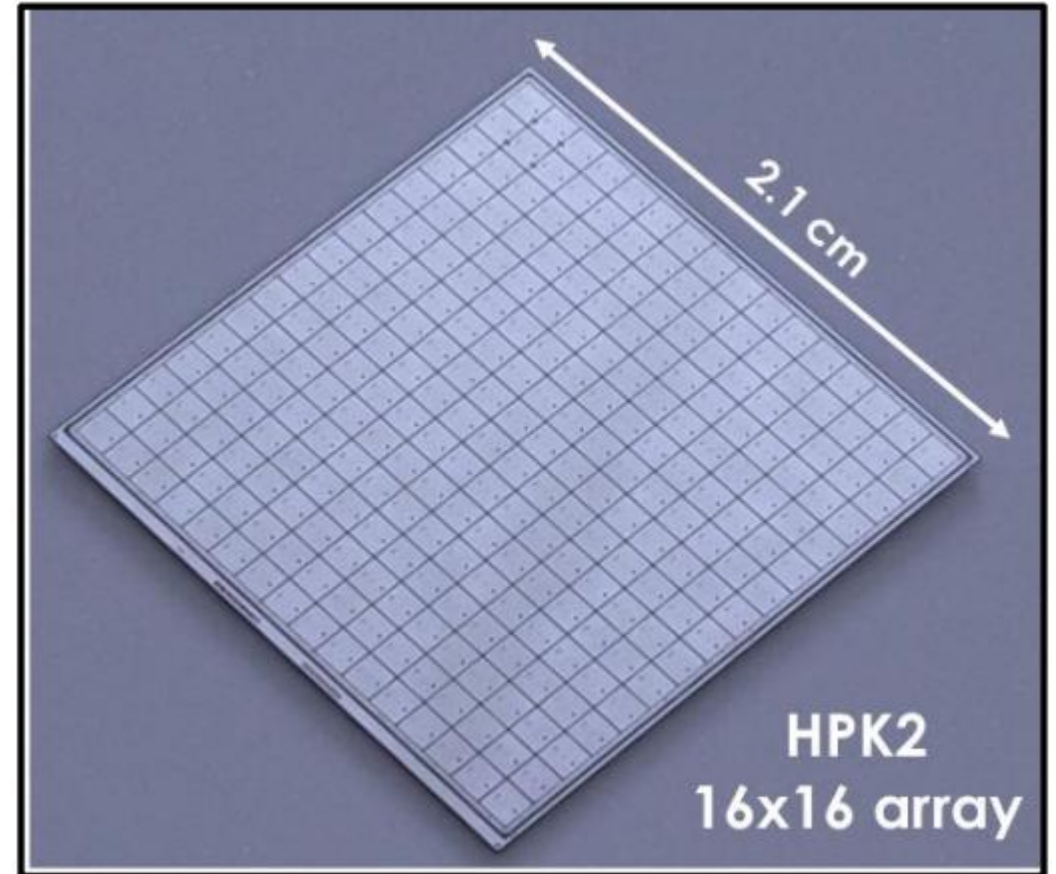
A schematic view of the MTD Endcap Timing Layer. The ETL will be instrumented with thin (50  $\mu$ m) silicon sensors based on the LGAD technology

# LGAD sensors for ETL

The final ETL sensor will be a 16x16 LGAD, to be bump-bonded to the ETL read-out chip (ETROC)

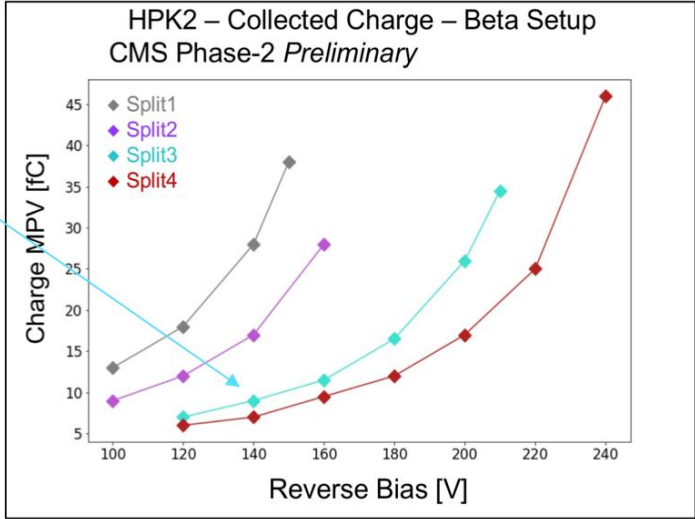
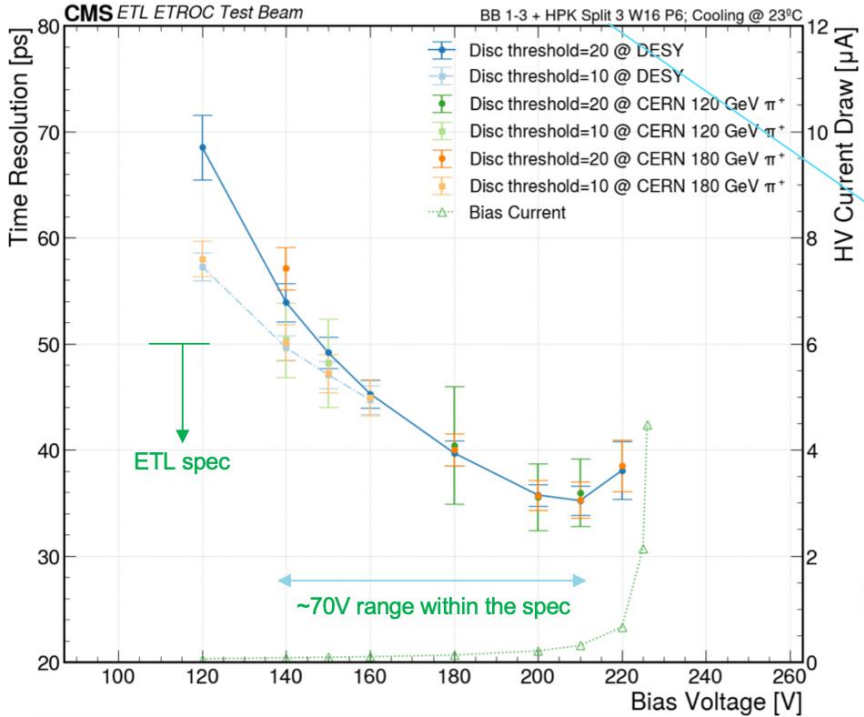
- 1.3 x 1.3 mm<sup>2</sup> pads for a total surface of 21.4 x 21.6 mm<sup>2</sup>
- From the beginning to the end of HL-LHC lifetime, sensors are expected to:
  - achieve time resolution < 50 ps
  - deliver > 8 fC

ETL sensors need also to be radiation-hard to survive the harsh radiation environment @ HL-LHC. The 1e15 neq/cm<sup>2</sup> threshold is set as it represents the turning point in terms of LGADs performance degradation.



# Beam test result for 16x16 sensor bump-bonding to ETROC

## ETROC2 beam test at DESY (June) and CERN (Aug and Sep 2024)



Successfully reproduced ~35ps res. with this board.  
 Results from CERN 120-180 GeV  $\pi^+$  beams agree  
 with those from DESY 4GeV  $e^-$  beam

Our ETL colleagues have done a series of beam tests for 16x16 sensor bump-bonding to ETROC. Check details below:

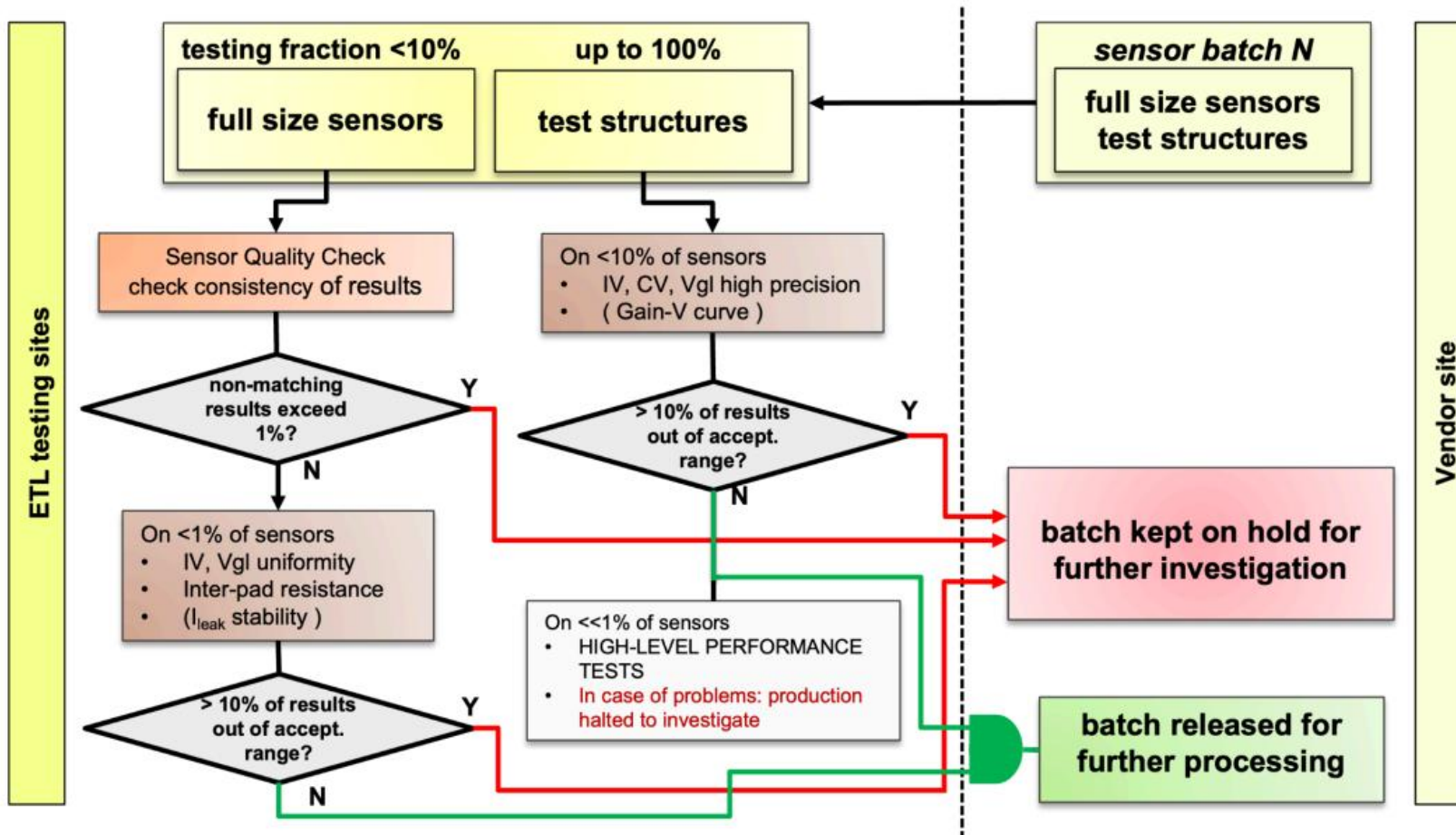
<https://indico.cern.ch/event/1381495/contributions/5988475/attachments/2938155/5161178/ETROC2-TWEPP-2024-final.pdf>



To be done: test in cold, and w/ irradiated sensors



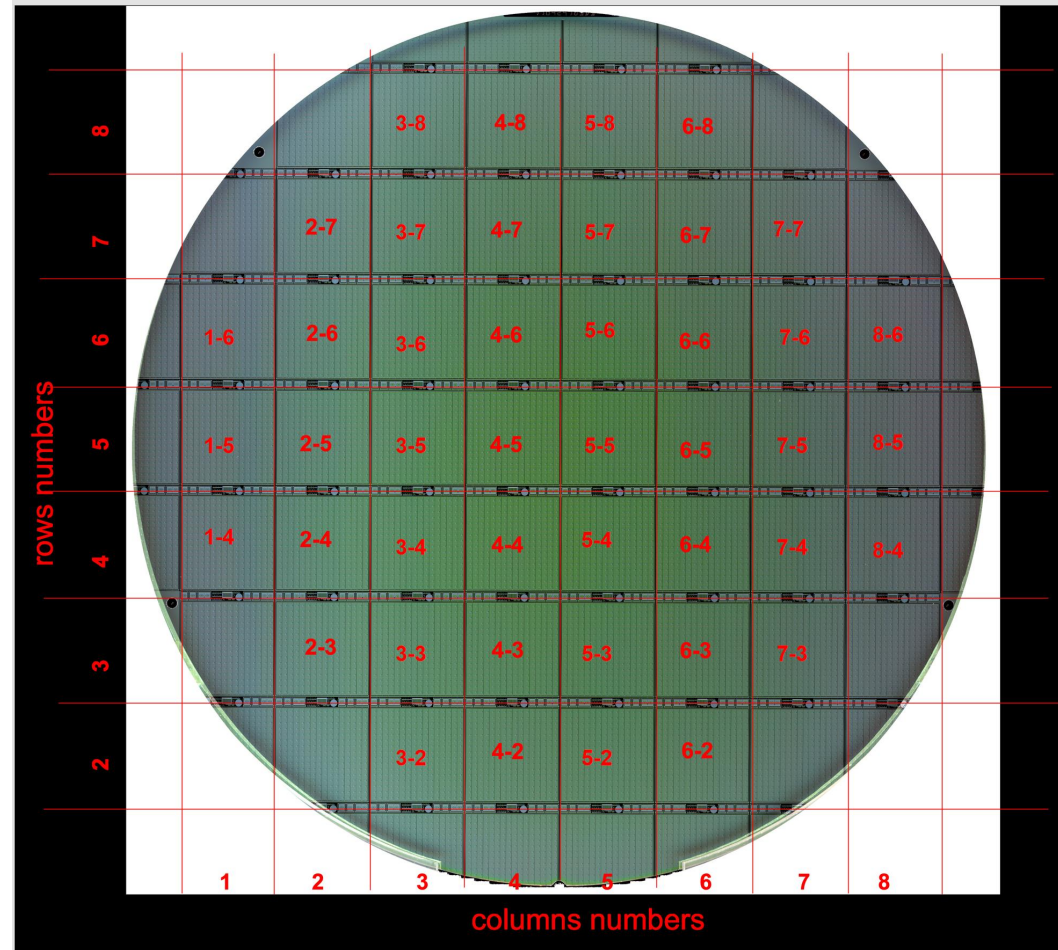
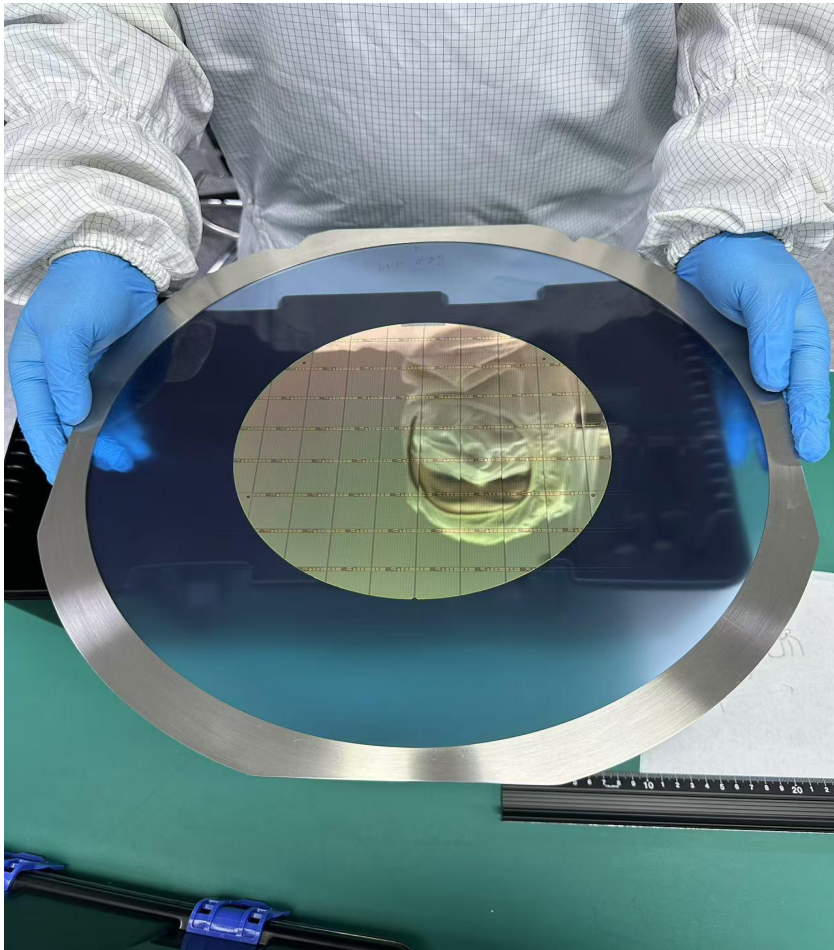
# ETL LGAD QA&QC plan



USTC will take both sensor and structures task.

And we have the unique capability to do the precise per channel IV measurement.

# Post process for FBK wafer

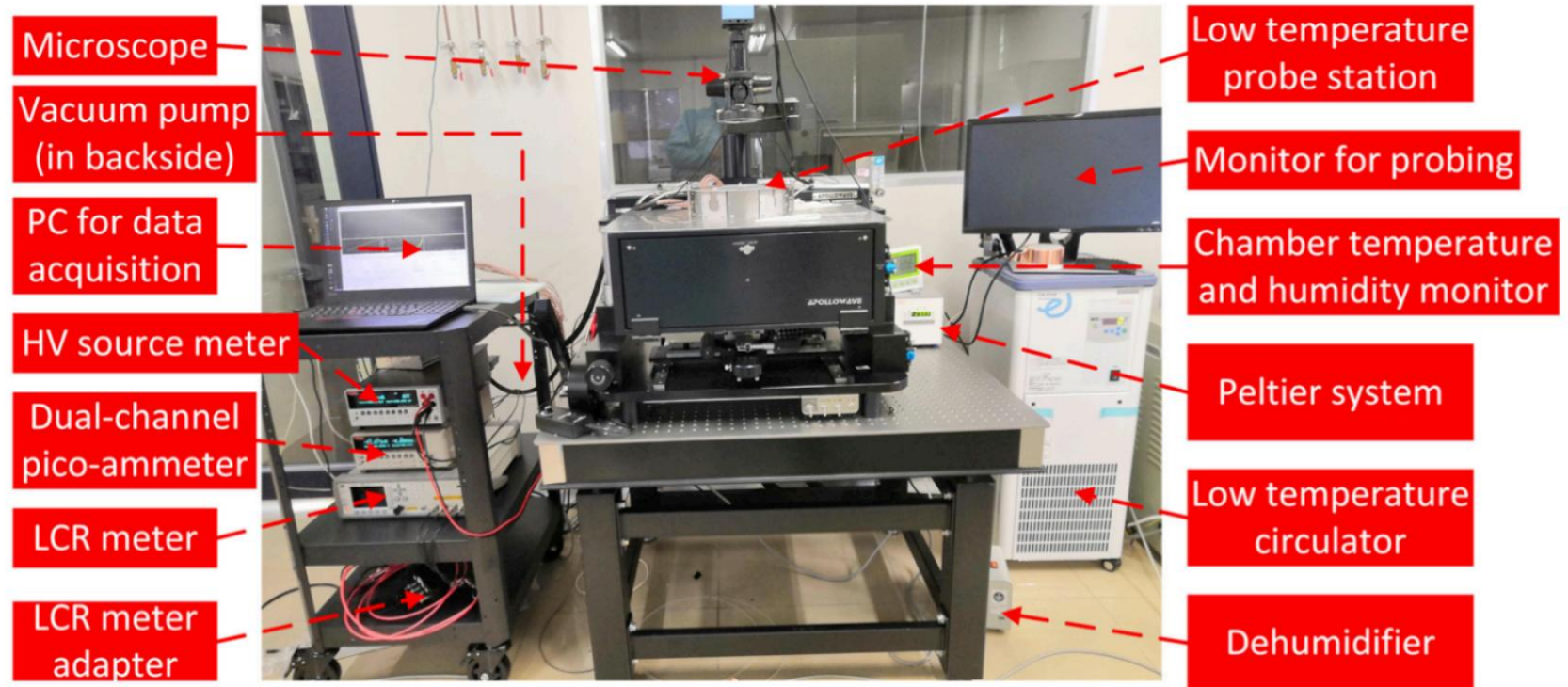


We have 4 FBK wafers post-processed by NCAP. This wafer will be tested in USTC&Torino lab to verify the post-processing result and the sensors will be used in the module assembly.



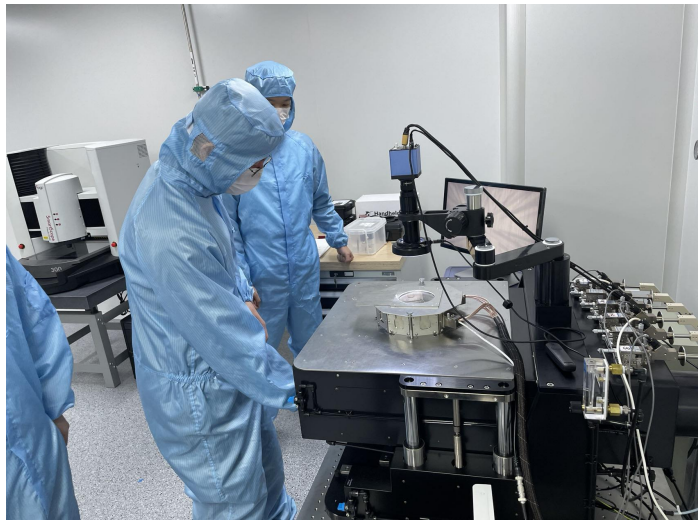
# Test environment in USTC

- single needle test system
  - ▶ Stable but slow, suitable for small number of sensors
- probe card test system
  - ▶ Complex but fast, suitable for large number of sensors
- Both systems are available at USTC.

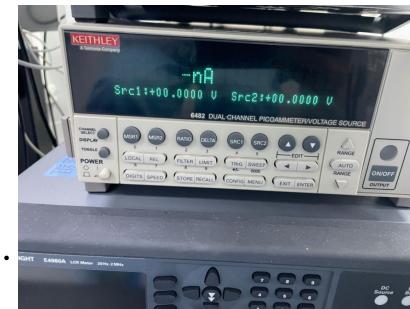




# Test environment in USTC



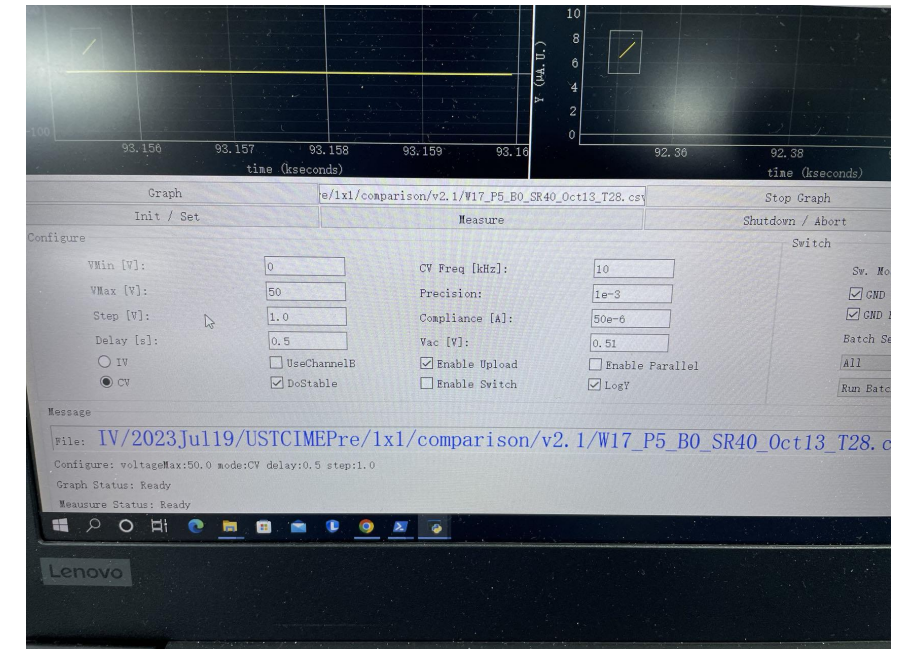
Keithley 2410



Keithley 6482

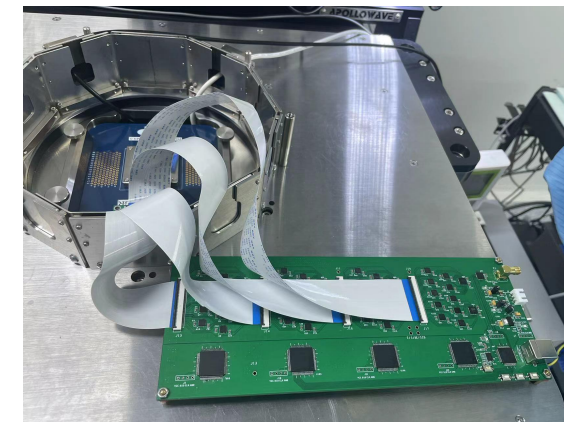
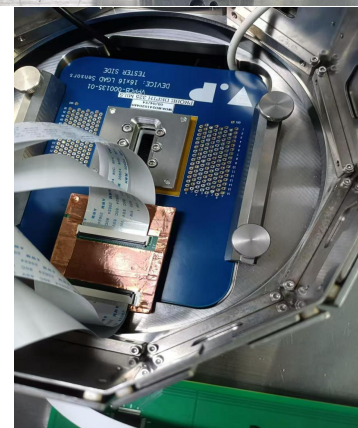
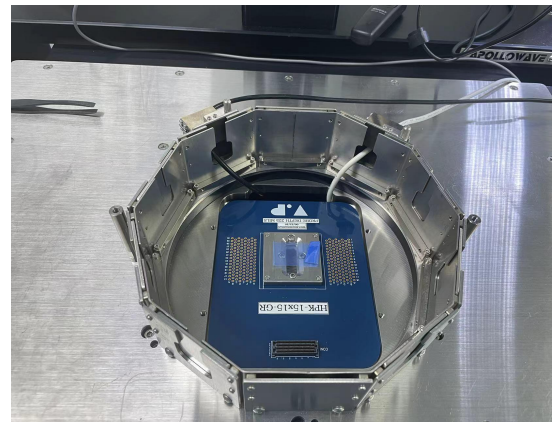
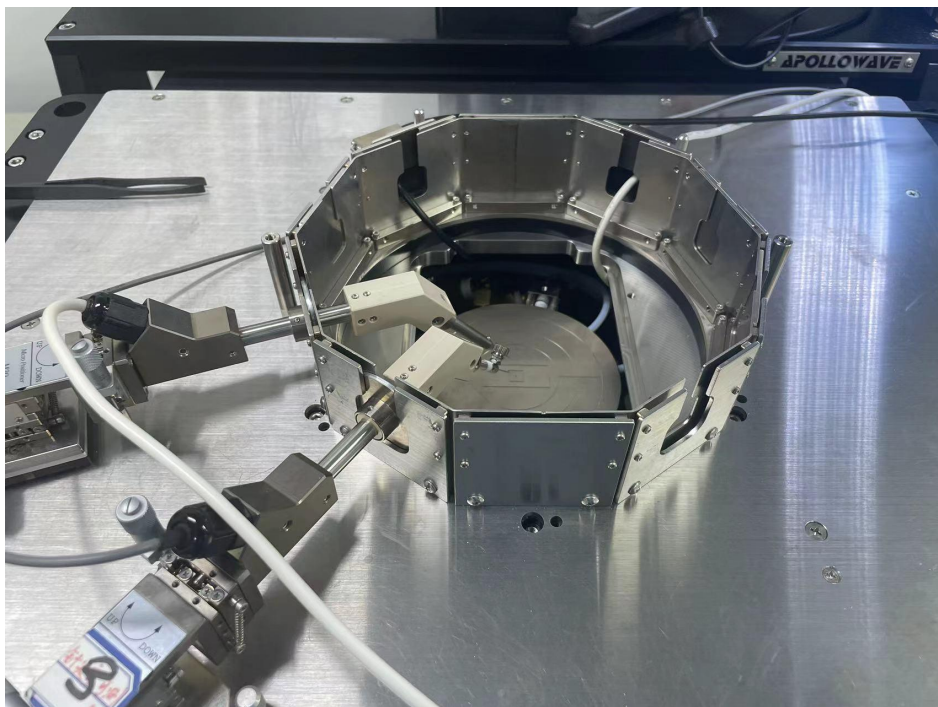


Keysight E4980A



The software UI we used to control the test parameter.

# Test environment in USTC



Probe station with up to 5 probes placed in the clean room. Temperature from  $-40$  to  $25$  degrees.

16\*16 probe card controlled by the switch matrix via interface pad  
The details of the electronics can be found below:

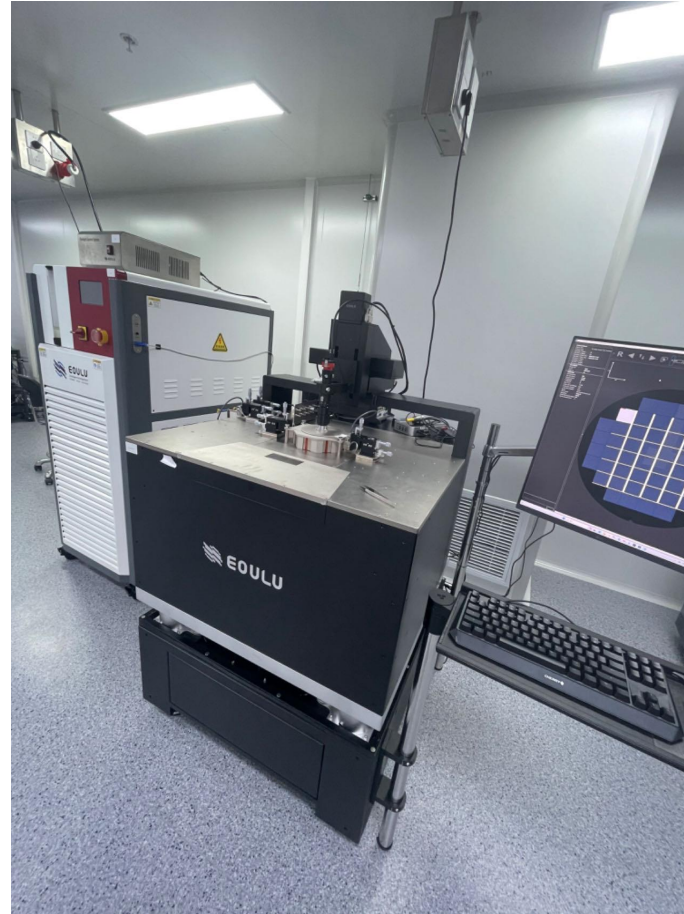
<https://www.sciencedirect.com/science/article/pii/S0168900221003843>



# Test environment in USTC

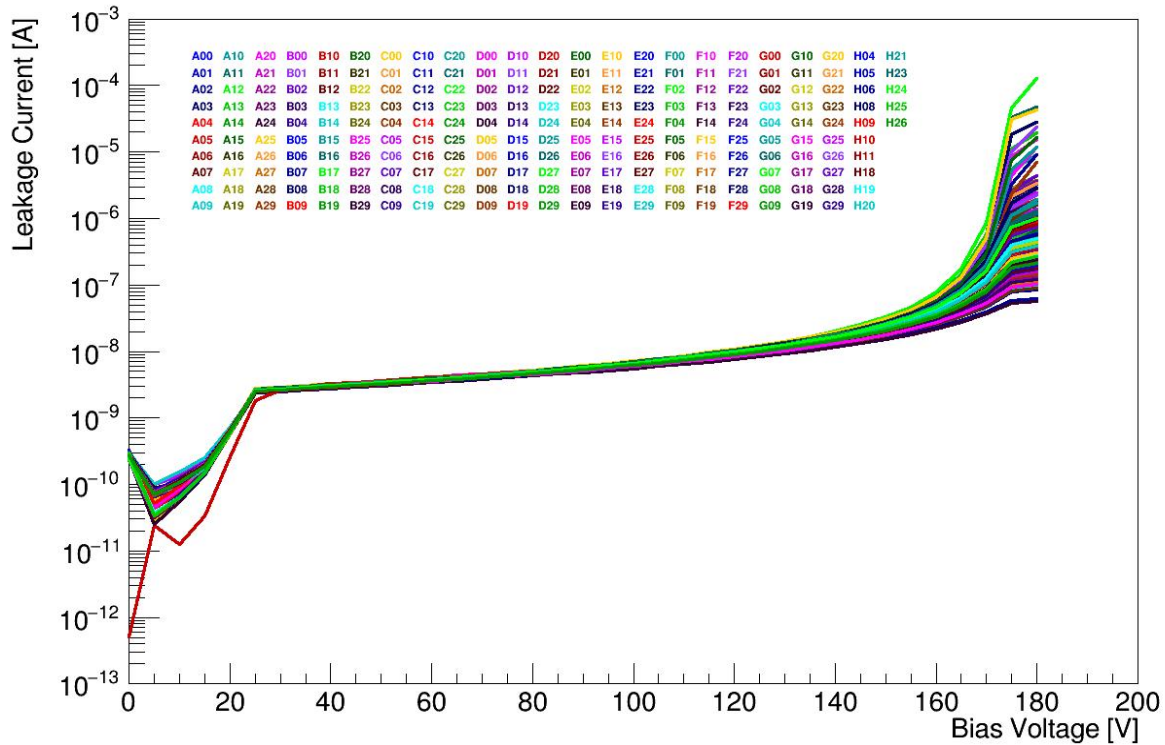
We also have an automatic probe station. Suitable for the wafer test.

This system is still under test. It will be put into use soon.

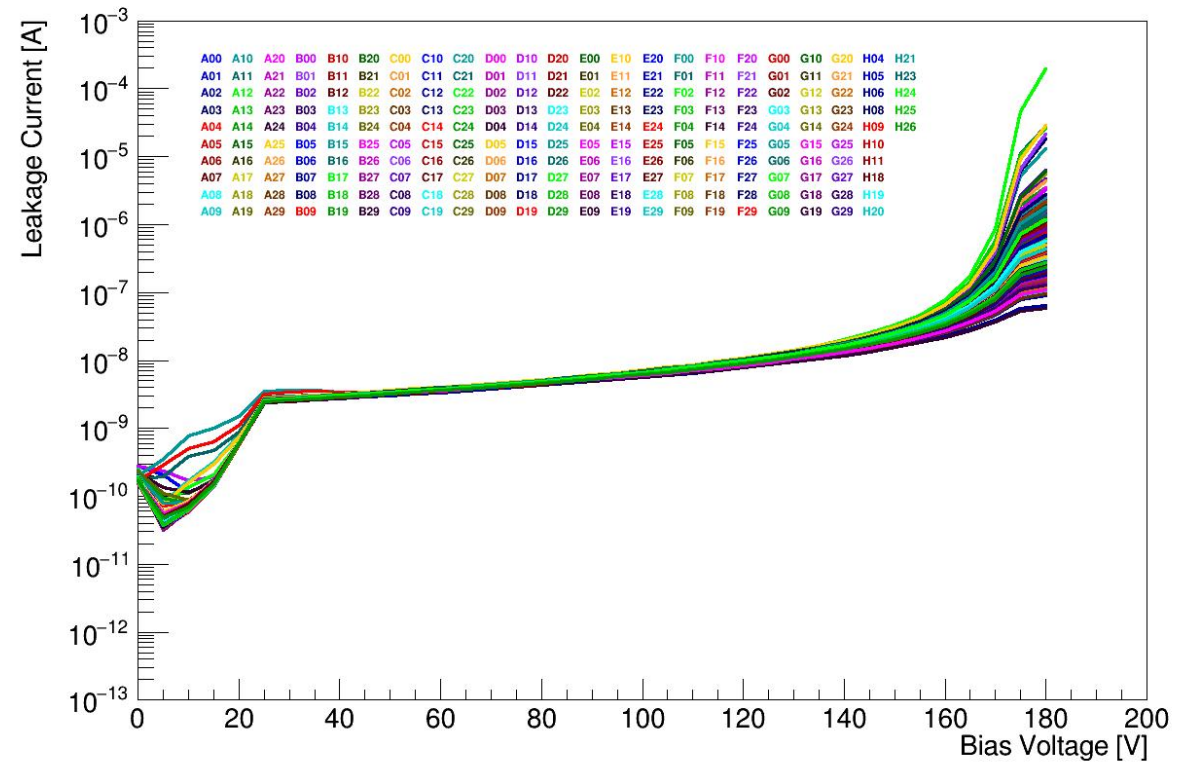


# Test result, 15\*15, IV

-ustcfs-HICUser-zhangzhan-sensortest-Aug26 [Log]



-ustcfs-HICUser-zhangzhan-sensortest-Aug262 [Log]



The 15x15 test results using our electronics. We tested a 15x15 sensor (225 sensor pads) with 2 sets of electronics (same design). The voltage step is 5V. Delay is 0.5 s. The total scan time for a 15x15 sensor is about 5 hours. The single pad scan time is about 2 s.



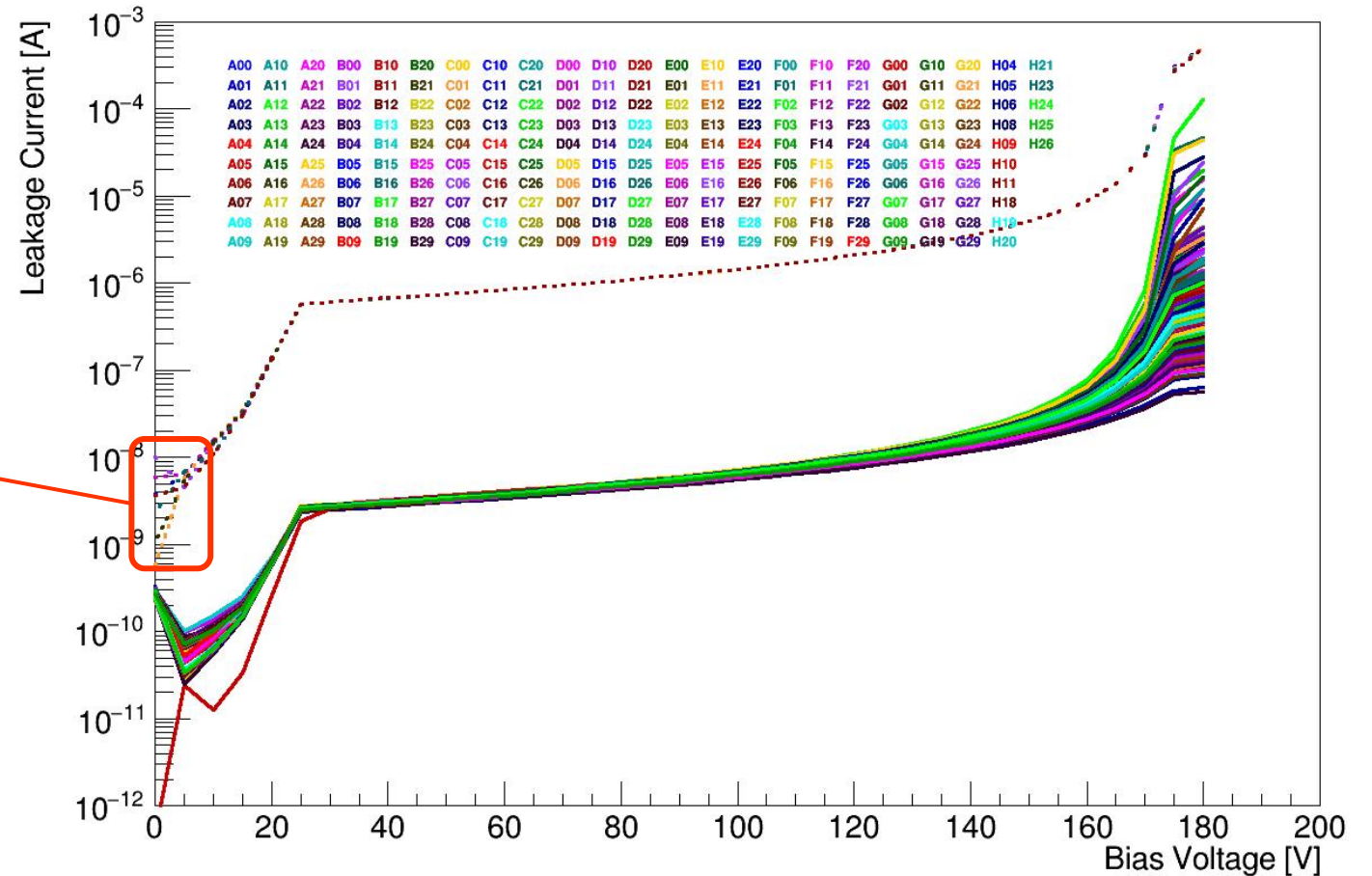
# Test result, 15\*15, IV

-ustcfs-HICUser-zhangzhan-sensortest-Aug26 [Log]

The total current and per channel current in the same plot.

The difference here is because of the 1 pA current precision of Keithley 2410.

We use the Keithley 6482 to read the per channel current and 2410 to read the total current. After depletion of sensor, the total current tend to be consistent.



# Summary

- Our test environment and setup are reliable and can perform both IV/CV tests from  $-40$  to  $25$  degrees. We also have the capability to conduct electrical property tests for Quality Control Test Structures (QC-TS).
- USTC plan to set up the LGAD QC site by Q1 2025.
- We will also participate in the ETL DAQ R&D process.